TECHNICAL DATA SHEET



DIC PSAs web page



Electrically conductive copper foil adhesive tape

DAITAC® E30CU

Construction



Characteristics

- ✓ Tape thickness is 30 μ m.
- ✓ Excellent electrical conductivity in thickness direction.
- ✓ Excellent adhesion
- ✓ Product does not use the 6 restrictive substances of the RoHS Directive.

Applications

✓ For EMI shielding of electronic equipment.

Properties

Test item	Condition	Substrate	Unit	E30CU
Thickness	Except release liner	-	μm	30
180 deg. peel strength	23°C, 1hr	SUS (hairline)	N/25mm	11
Electrical resistance	Pressure method	Copper foil	Ω/6.25cm²	0.01
	Attached method	Copper foil	$\Omega/6.25$ cm²	0.02
Static shear	70°C, 0.5kg	SUS (hairline)	hr	24 <

Size

1,000mm in max width

50m in length